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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, I ² C, IrDA, SD, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I ² S, LVD, POR, PWM, WDT
Number of I/O	100
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 41x16b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk24fn1m0vlq12r

Kinetis K24 Family

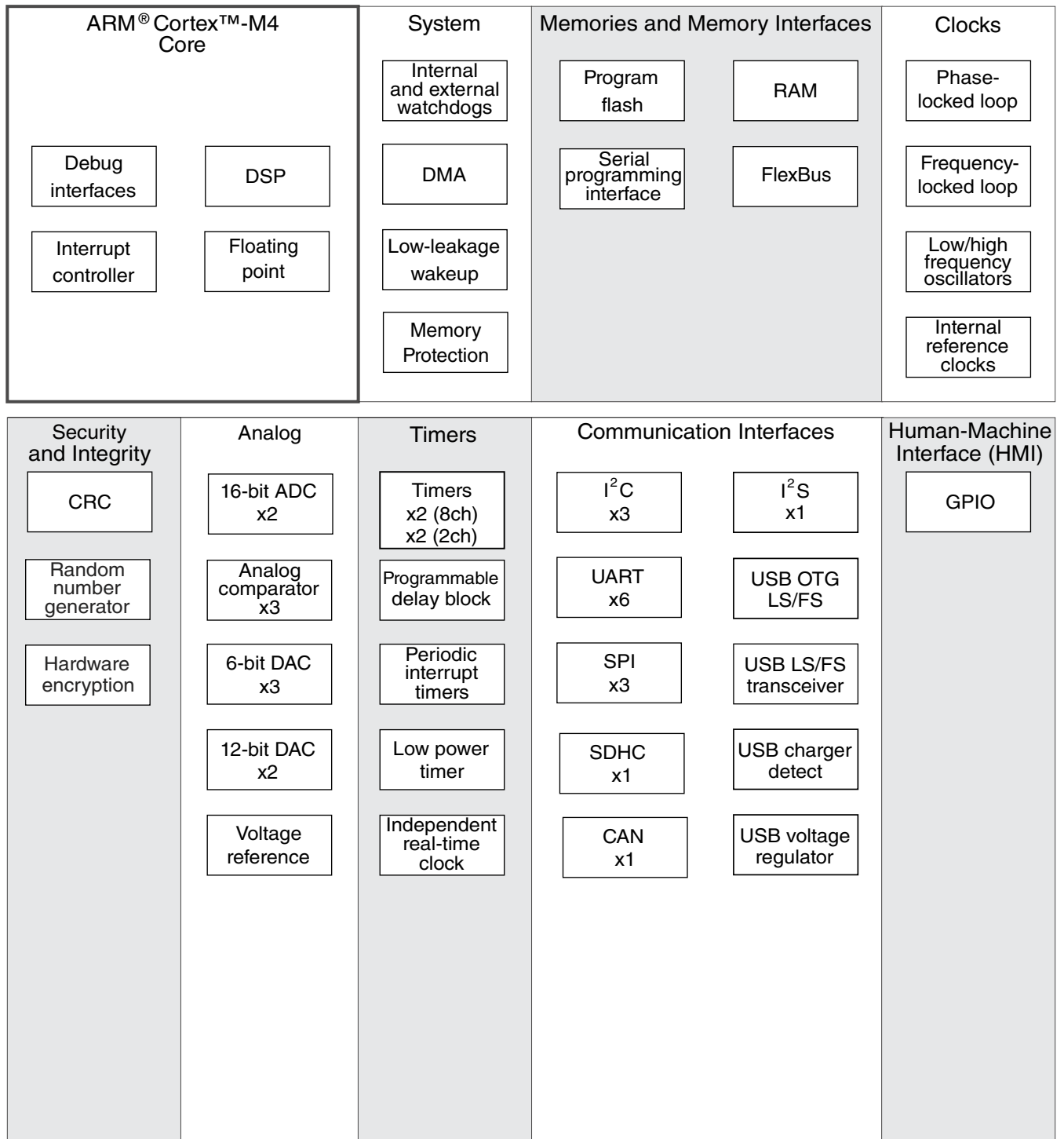


Figure 1. K24 block diagram

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Max.	Unit	Notes
I_{OZ}	Hi-Z (off-state) leakage current (per pin)	—	0.25	μA	
$I_{OZ_RTC_WAKEUP}$	Hi-Z (off-state) leakage current (per RTC_WAKEUP pin)	—	0.25	μA	
R_{PU}	Internal pullup resistors (except RTC_WAKEUP pins)	20	50	$k\Omega$	2
R_{PD}	Internal pulldown resistors (except RTC_WAKEUP pins)	20	50	$k\Omega$	3

1. Measured at $V_{DD}=3.6V$

2. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{SS}$

3. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR} , and $VLLSx \rightarrow RUN$ recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus clock = 50 MHz
- FlexBus clock = 50 MHz
- Flash clock = 25 MHz

Table 5. Power mode transition operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
t_{POR}	After a POR event, amount of time from the point V_{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip.	—	300	μs	
	• $VLLS0 \rightarrow RUN$	—	156	μs	
	• $VLLS1 \rightarrow RUN$	—	156	μs	
	• $VLLS2 \rightarrow RUN$	—	78	μs	
	• $VLLS3 \rightarrow RUN$	—	78	μs	
	• $LLS \rightarrow RUN$	—	4.8	μs	
	• $VLPS \rightarrow RUN$	—	4.5	μs	
	• $STOP \rightarrow RUN$	—	4.5	μs	

2.2.5 Power consumption operating behaviors

NOTE

The maximum values represent characterized results equivalent to the mean plus three times the standard deviation (mean + 3 sigma).

Table 6. Power consumption operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I _{DDA}	Analog supply current	—	—	See note	mA	1
I _{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash	—	31.1	36.65	mA	2
		—	31	36.75	mA	
I _{DD_RUN}	Run mode current — all peripheral clocks enabled, code executing from flash	—	42.7	48.35	mA	3, 4
		—	40	41.60	mA	
		—	48.33	51.50	mA	
		—	48.33	51.50	mA	
I _{DD_WAIT}	Wait mode high frequency current at 3.0 V — all peripheral clocks disabled	—	17.9	—	mA	2
I _{DD_WAIT}	Wait mode reduced frequency current at 3.0 V — all peripheral clocks disabled	—	6.9	—	mA	5
I _{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks disabled	—	1.0	—	mA	6
I _{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks enabled	—	1.7	—	mA	7
I _{DD_VLPW}	Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled	—	0.678	—	mA	8
I _{DD_STOP}	Stop mode current at 3.0 V	—	0.49	1.24	mA	
		—	1.18	4.3	mA	
		—	3.0	12.5	mA	
I _{DD_VLPS}	Very-low-power stop mode current at 3.0 V	—	57	139.31	μA	
		—	291	679.33	μA	
		—	927.3	1869.85	μA	
I _{DD_LLS}	Low leakage stop mode current at 3.0 V	—	—	—	—	9

Table continues on the next page...

Table 7. Low power mode peripheral adders — typical value (continued)

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
	entering all modes with the crystal enabled.	440	490	540	560	570	580	nA
	VLLS1	440	490	540	560	570	580	
	VLLS3	490	490	540	560	570	680	
	LLS	510	560	560	560	610	680	
	VLPS	510	560	560	560	610	680	
	STOP							
I _{48MIRC}	48 Mhz internal reference clock	350	350	350	350	350	350	μA
I _{CMP}	CMP peripheral adder measured by placing the device in VLLS1 mode with CMP enabled using the 6-bit DAC and a single external input for compare. Includes 6-bit DAC power consumption.	22	22	22	22	22	22	μA
I _{RTC}	RTC peripheral adder measured by placing the device in VLLS1 mode with external 32 kHz crystal enabled by means of the RTC_CR[OSCE] bit and the RTC ALARM set for 1 minute. Includes ERCLK32K (32 kHz external crystal) power consumption.	432	357	388	475	532	810	nA
I _{UART}	UART peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source waiting for RX data at 115200 baud rate. Includes selected clock source power consumption.							μA
	MCGIRCLK (4 MHz internal reference clock)	66	66	66	66	66	66	
	OSCERCLK (4 MHz external crystal)	214	237	246	254	260	268	
I _{BG}	Bandgap adder when BGEN bit is set and device is placed in VLPx, LLS, or VLLSx mode.	45	45	45	45	45	45	μA
I _{ADC}	ADC peripheral adder combining the measured values at V _{DD} and V _{DDA} by placing the device in STOP or VLPS mode. ADC is configured for low power mode using the internal clock and continuous conversions.	42	42	42	42	42	42	μA

2.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

Wideband TEM Cell Method. Measurements were made while the microcontroller was running basic application code. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.

2. $V_{DD} = 3.3\text{ V}$, $T_A = 25\text{ °C}$, $f_{OSC} = 12\text{ MHz}$ (crystal), $f_{SYS} = 96\text{ MHz}$, $f_{BUS} = 48\text{ MHz}$
3. Specified according to Annex D of IEC Standard 61967-2, *Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*

2.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to www.nxp.com.
2. Perform a keyword search for “EMC design.”

2.2.8 Capacitance attributes

Table 9. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C_{IN_A}	Input capacitance: analog pins	—	7	pF
C_{IN_D}	Input capacitance: digital pins	—	7	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 10. Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
Normal run mode					
f_{SYS}	System and core clock	—	120	MHz	
	System and core clock when Full Speed USB in operation	20	—	MHz	
f_{BUS}	Bus clock	—	60	MHz	
FB_CLK	FlexBus clock	—	50	MHz	
f_{FLASH}	Flash clock	—	25	MHz	
f_{LPTMR}	LPTMR clock	—	25	MHz	
VLPR mode ¹					
f_{SYS}	System and core clock	—	4	MHz	

Table continues on the next page...

Table 10. Device clock specifications (continued)

Symbol	Description	Min.	Max.	Unit	Notes
f_{BUS}	Bus clock	—	4	MHz	
FB_CLK	FlexBus clock	—	4	MHz	
f_{FLASH}	Flash clock	—	0.8	MHz	
f_{ERCLK}	External reference clock	—	16	MHz	
$f_{\text{LPTMR_pin}}$	LPTMR clock	—	25	MHz	
$f_{\text{LPTMR_ERCLK}}$	LPTMR external reference clock	—	16	MHz	
$f_{\text{FlexCAN_ERCLK}}$	FlexCAN external reference clock	—	8	MHz	
$f_{\text{I2S_MCLK}}$	I2S master clock	—	12.5	MHz	
$f_{\text{I2S_BCLK}}$	I2S bit clock	—	4	MHz	

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.

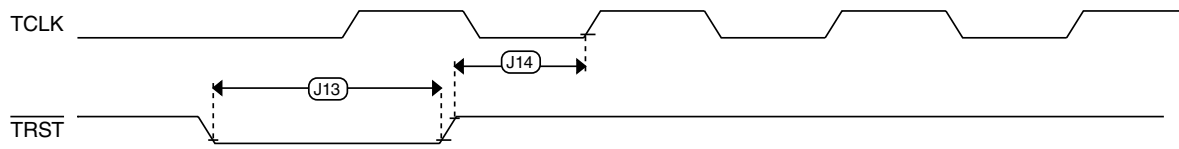
2.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, CAN, CMT, timers, and I²C signals.

Table 11. General switching specifications

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1, 2
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter enabled) — Asynchronous path	100	—	ns	3
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter disabled) — Asynchronous path	50	—	ns	3
	External reset pulse width (digital glitch filter disabled)	100	—	ns	3
	Mode select ($\overline{\text{EZP_CS}}$) hold time after reset deassertion	2	—	Bus clock cycles	
	Port rise and fall time (high drive strength) - 3 V				4
	- Slew disabled $1.71 \leq V_{\text{DD}} \leq 2.7\text{V}$ $2.7 \leq V_{\text{DD}} \leq 3.6\text{V}$ - Slew enabled $1.71 \leq V_{\text{DD}} \leq 2.7\text{V}$ $2.7 \leq V_{\text{DD}} \leq 3.6\text{V}$	— — — —	8 6 18 12	ns ns ns ns	
	Port rise and fall time (high drive strength) - 5 V				4
	Slew disabled				

Table continues on the next page...

Figure 10. $\overline{\text{TRST}}$ timing

3.2 System modules

There are no specifications necessary for the device's system modules.

3.3 Clock modules

3.3.1 MCG specifications

Table 17. MCG specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{\text{ints_ft}}$	Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C	—	32.768	—	kHz	
$f_{\text{ints_t}}$	Internal reference frequency (slow clock) — user trimmed	31.25	—	39.0625	kHz	
I_{ints}	Internal reference (slow clock) current	—	20	—	μA	
$\Delta f_{\text{dco_res_t}}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM	—	± 0.3	± 0.6	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco_res_t}}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM only	—	± 0.2	± 0.5	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over voltage and temperature	—	± 0.5	± 2	$\%f_{\text{dco}}$	1, 2
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C	—	± 0.3	± 1	$\%f_{\text{dco}}$	1
$f_{\text{intf_ft}}$	Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C	—	4	—	MHz	
$f_{\text{intf_t}}$	Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C	3	—	5	MHz	
I_{intf}	Internal reference (fast clock) current	—	25	—	μA	

Table continues on the next page...

Table 18. IRC48M specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$\Delta f_{irc48m_ol_hv}$	Open loop total deviation of IRC48M frequency at high voltage (VDD=1.89V-3.6V) over 0 to 85 °C Regulator enable (USB_CLK_RECOVER_IRC_EN[REG_EN]=1)	—	± 0.5	± 1.0	% f_{irc48m}	1
Δf_{irc48m_cl}	Closed loop total deviation of IRC48M frequency over voltage and temperature	—	—	± 0.1	% f_{host}	2
J_{cyc_irc48m}	Period Jitter (RMS)	—	35	150	ps	
$t_{irc48mst}$	Startup time	—	2	3	μs	3

1. The maximum value represents characterized results equivalent to the mean plus or minus three times the standard deviation (mean ± 3 sigma)
2. Closed loop operation of the IRC48M is only feasible for USB device operation; it is not usable for USB host operation. It is enabled by configuring for USB Device, selecting IRC48M as USB clock source, and enabling the clock recover function (USB_CLK_RECOVER_IRC_CTRL[CLOCK_RECOVER_EN]=1, USB_CLK_RECOVER_IRC_EN[IRC_EN]=1).
3. IRC48M startup time is defined as the time between clock enablement and clock availability for system use. Enable the clock by setting USB_CLK_RECOVER_IRC_EN[IRC_EN]=1.

3.3.3 Oscillator electrical specifications

3.3.3.1 Oscillator DC electrical specifications

Table 19. Oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	—	3.6	V	
I_{DDOSC}	Supply current — low-power mode (HGO=0) 32 kHz 4 MHz 8 MHz (RANGE=01) 16 MHz 24 MHz 32 MHz	—	500	—	nA	1
		—	200	—	μA	
		—	300	—	μA	
		—	950	—	μA	
		—	1.2	—	mA	
		—	1.5	—	mA	
I_{DDOSC}	Supply current — high-gain mode (HGO=1) 32 kHz 4 MHz 8 MHz (RANGE=01) 16 MHz 24 MHz 32 MHz	—	25	—	μA	1
		—	400	—	μA	
		—	500	—	μA	
		—	2.5	—	mA	
		—	3	—	mA	
		—	4	—	mA	

Table continues on the next page...

3.3.3.2 Oscillator frequency specifications

Table 20. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc_hi_1}$	Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01)	3	—	8	MHz	
$f_{osc_hi_2}$	Oscillator crystal or resonator frequency — high-frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
f_{ec_extal}	Input clock frequency (external clock mode)	—	—	50	MHz	1, 2
t_{dc_extal}	Input clock duty cycle (external clock mode)	40	50	60	%	
t_{cst}	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	750	—	ms	3, 4
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	250	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	0.6	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	1	—	ms	

1. Other frequency limits may apply when external clock is being used as a reference for the FLL
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

NOTE

The 32 kHz oscillator works in low power mode by default and cannot be moved into high power/gain mode.

3.3.4 32 kHz oscillator electrical characteristics

3.3.4.1 32 kHz oscillator DC electrical specifications

Table 21. 32kHz oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{BAT}	Supply voltage	1.71	—	3.6	V
R_F	Internal feedback resistor	—	100	—	MΩ

Table continues on the next page...

- Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 24. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1blk512k}$	Read 1s Block execution time • 512 KB program flash	—	—	1.8	ms	
$t_{rd1sec4k}$	Read 1s Section execution time (4 KB flash)	—	—	100	μs	1
t_{pgmchk}	Program Check execution time	—	—	95	μs	1
t_{rdsrc}	Read Resource execution time	—	—	40	μs	1
t_{pgm8}	Program Phrase execution time	—	90	150	μs	
$t_{ersblk512k}$	Erase Flash Block execution time • 512 KB program flash	—	435	3700	ms	2
t_{ersscr}	Erase Flash Sector execution time	—	15	115	ms	2
$t_{rd1alln}$	Read 1s All Blocks execution time • Program flash only devices	—	—	3.4	ms	
t_{rdonce}	Read Once execution time	—	—	30	μs	1
$t_{pgmonce}$	Program Once execution time	—	70	—	μs	
t_{ersall}	Erase All Blocks execution time	—	870	7400	ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	μs	1
$t_{swapx01}$	Swap Control execution time • control code 0x01	—	200	—	μs	
$t_{swapx02}$	• control code 0x02	—	70	150	μs	
$t_{swapx04}$	• control code 0x04	—	70	150	μs	
$t_{swapx08}$	• control code 0x08	—	—	30	μs	

- Assumes 25MHz or greater flash clock frequency.
- Maximum times for erase parameters based on expectations at cycling end-of-life.

3.4.1.3 Flash high voltage current behaviors

Table 25. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I_{DD_PGM}	Average current adder during high voltage flash programming operation	—	3.5	7.5	mA
I_{DD_ERS}	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

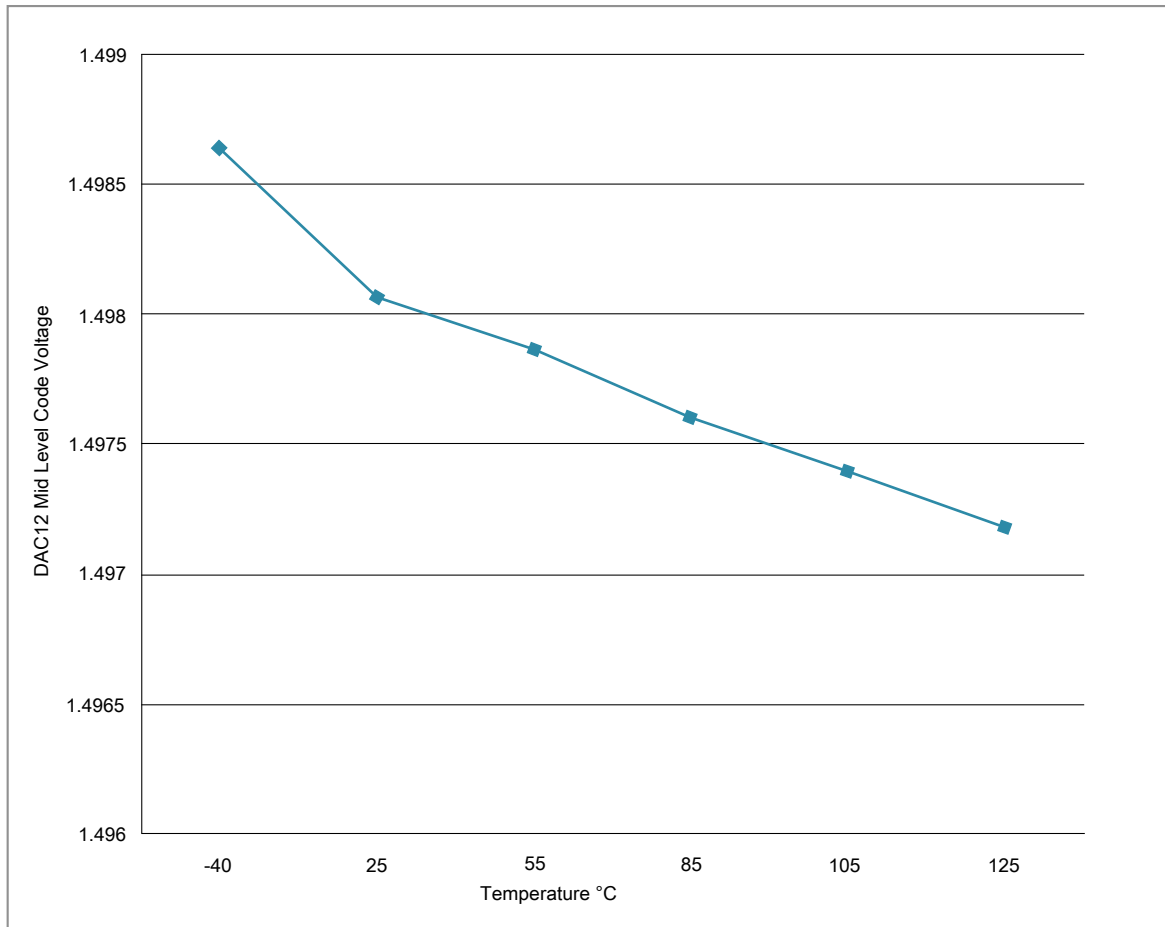


Figure 20. Offset at half scale vs. temperature

3.6.4 Voltage reference electrical specifications

Table 35. VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	—
T_A	Temperature	Operating temperature range of the device		°C	—
C_L	Output load capacitance	100		nF	1, 2

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.
2. The load capacitance should not exceed +/-25% of the nominal specified C_L value over the operating temperature range of the device.

3.8.5 DSPI switching specifications (limited voltage range)

The DMA Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the DSPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 41. Master mode DSPI timing (limited voltage range)

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	30	MHz	
DS1	DSPI_SCK output cycle time	$2 \times t_{\text{BUS}}$	—	ns	
DS2	DSPI_SCK output high/low time	$(t_{\text{SCK}}/2) - 2$	$(t_{\text{SCK}}/2) + 2$	ns	
DS3	DSPI_PCSn valid to DSPI_SCK delay	$(t_{\text{BUS}} \times 2) - 2$	—	ns	1
DS4	DSPI_SCK to DSPI_PCSn invalid delay	$(t_{\text{BUS}} \times 2) - 2$	—	ns	2
DS5	DSPI_SCK to DSPI_SOUT valid	—	8.5	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-2	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	15	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

1. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].
2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

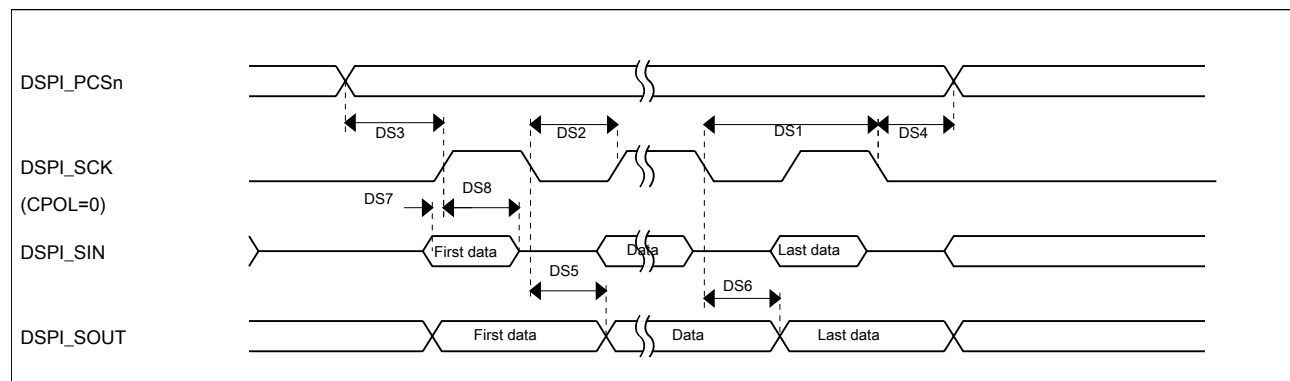


Figure 21. DSPI classic SPI timing — master mode

Table 42. Slave mode DSPI timing (limited voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
	Frequency of operation		15 ¹	MHz

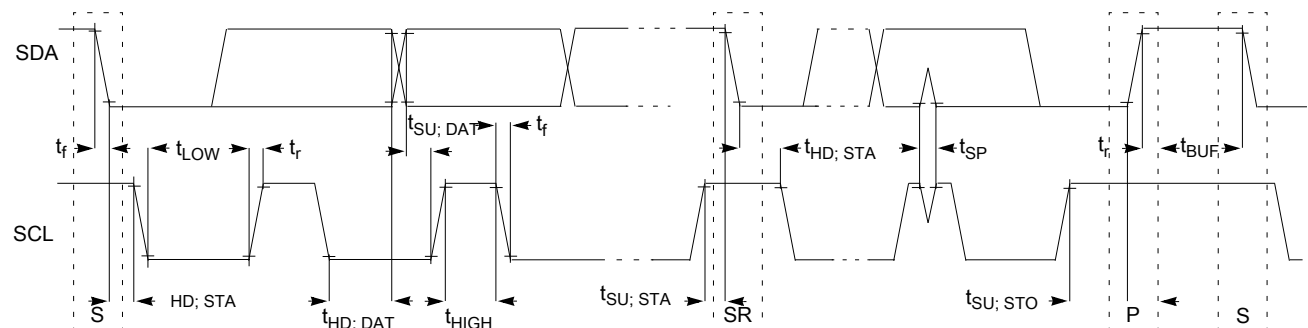
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6. A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement $t_{\text{SU; DAT}} \geq 250$ ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{\text{rmax}} + t_{\text{SU; DAT}} = 1000 + 250 = 1250$ ns (according to the Standard mode I²C bus specification) before the SCL line is released.
7. C_b = total capacitance of the one bus line in pF.

Table 46. I²C 1 Mbps timing

Characteristic	Symbol	Minimum	Maximum	Unit
SCL Clock Frequency	f_{SCL}	0	1 ¹	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	$t_{\text{HD; STA}}$	0.26	—	μs
LOW period of the SCL clock	t_{LOW}	0.5	—	μs
HIGH period of the SCL clock	t_{HIGH}	0.26	—	μs
Set-up time for a repeated START condition	$t_{\text{SU; STA}}$	0.26	—	μs
Data hold time for I ² C bus devices	$t_{\text{HD; DAT}}$	0	—	μs
Data set-up time	$t_{\text{SU; DAT}}$	50	—	ns
Rise time of SDA and SCL signals	t_r	$20 + 0.1C_b$ ²	120	ns
Fall time of SDA and SCL signals	t_f	$20 + 0.1C_b$ ²	120	ns
Set-up time for STOP condition	$t_{\text{SU; STO}}$	0.26	—	μs
Bus free time between STOP and START condition	t_{BUF}	0.5	—	μs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

1. The maximum SCL clock frequency of 1 Mbps can support maximum bus loading when using the High drive pins across the full voltage range.
2. C_b = total capacitance of the one bus line in pF.

**Figure 25. Timing definition for devices on the I²C bus**

3.8.8 UART switching specifications

See [General switching specifications](#).

Table 53. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S18	I2S_RXD hold after I2S_RX_BCLK	11	—	ns
S19	I2S_TX_FS input assertion to I2S_TXD output valid ¹	—	72	ns

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

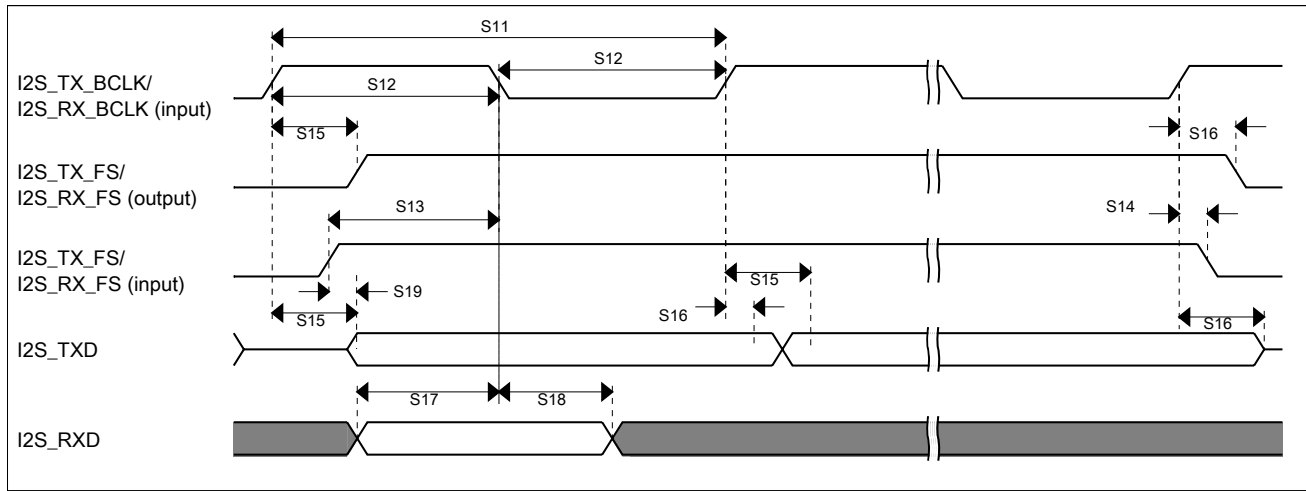


Figure 32. I2S/SAI timing — slave modes

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
100-pin LQFP	98ASS23308W
121-pin XFBGA	98ASA00595D
144-pin LQFP	98ASS23177W

Pinout

144 QFP	100 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9
6	—	VSS	VSS										
7	5	DISABLED		PTE4/ LLWU_P2	SPI1_PCS0	UART3_TX	SDHC0_D3	TRACE_D0				LLWU_P2	
8	6	DISABLED		PTE5	SPI1_PCS2	UART3_RX	SDHC0_D2		FTM3_CH0				
9	7	DISABLED		PTE6/ x_LLWU_ P16	SPI1_PCS3	UART3_ CTS_b	I2S0_MCLK		FTM3_CH1	USB_SOF_ OUT		x_LLWU_ P16	
10	—	DISABLED		PTE7		UART3_ RTS_b	I2S0_RXD0		FTM3_CH2				
11	—	DISABLED		PTE8	I2S0_RXD1	UART5_TX	I2S0_RX_ FS		FTM3_CH3				
12	—	DISABLED		PTE9/ x_LLWU_ P17	I2S0_TXD1	UART5_RX	I2S0_RX_ BCLK		FTM3_CH4			x_LLWU_ P17	
13	—	DISABLED		PTE10/ x_LLWU_ P18		UART5_ CTS_b	I2S0_TXD0		FTM3_CH5			x_LLWU_ P18	
14	—	DISABLED		PTE11		UART5_ RTS_b	I2S0_TX_ FS		FTM3_CH6				
15	—	DISABLED		PTE12			I2S0_TX_ BCLK		FTM3_CH7				
16	8	VDD	VDD										
17	9	VSS	VSS										
18	—	VSS	VSS										
19	10	USB0_DP	USB0_DP										
20	11	USB0_DM	USB0_DM										
21	12	VOOUT33	VOOUT33										
22	13	VREGIN	VREGIN										
23	14	ADC0_DP1	ADC0_DP1										
24	15	ADC0_DM1	ADC0_DM1										
25	16	ADC1_DP1	ADC1_DP1										
26	17	ADC1_DM1	ADC1_DM1										
27	18	ADC0_ DP0/ ADC1_DP3	ADC0_ DP0/ ADC1_DP3										
28	19	ADC0_ DM0/ ADC1_DM3	ADC0_ DM0/ ADC1_DM3										
29	20	ADC1_ DP0/ ADC0_DP3	ADC1_ DP0/ ADC0_DP3										
30	21	ADC1_ DM0/ ADC0_DM3	ADC1_ DM0/ ADC0_DM3										
31	22	VDDA	VDDA										

Pinout

144 QFP	100 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9
50	34	JTAG_TCLK/ SWD_CLK/ EZP_CLK		PTA0	UART0_CTS_b/ UART0_COL_b	FTM0_CH5				JTAG_TCLK/ SWD_CLK			EZP_CLK
51	35	JTAG_TDI/ EZP_DI		PTA1	UART0_RX	FTM0_CH6				JTAG_TDI			EZP_DI
52	36	JTAG_TDO/ TRACE_SWO/ EZP_DO		PTA2	UART0_TX	FTM0_CH7				JTAG_TDO/ TRACE_SWO			EZP_DO
53	37	JTAG_TMS/ SWD_DIO		PTA3	UART0_RTS_b	FTM0_CH0				JTAG_TMS/ SWD_DIO			
54	38	NMI_b/ EZP_CS_b		PTA4/ LLWU_P3		FTM0_CH1				NMI_b		LLWU_P3	EZP_CS_b
55	39	DISABLED		PTA5	USB_CLKIN	FTM0_CH2	RMII0_RXER/ MII0_RXER	CMP2_OUT	I2S0_TX_BCLK	JTAG_TRST_b			
56	40	VDD	VDD										
57	41	VSS	VSS										
58	—	DISABLED		PTA6		FTM0_CH3		CLKOUT		TRACE_CLKOUT			
59	—	ADC0_SE10	ADC0_SE10	PTA7		FTM0_CH4				TRACE_D3			
60	—	ADC0_SE11	ADC0_SE11	PTA8		FTM1_CH0			FTM1_QD_PHA	TRACE_D2			
61	—	DISABLED		PTA9		FTM1_CH1	MII0_RXD3		FTM1_QD_PHB	TRACE_D1			
62	—	DISABLED		PTA10/ x_LLWU_P22		FTM2_CH0	MII0_RXD2		FTM2_QD_PHA	TRACE_D0		x_LLWU_P22	
63	—	DISABLED		PTA11/ x_LLWU_P23		FTM2_CH1	MII0_RXCLK	I2C2_SDA	FTM2_QD_PHB			x_LLWU_P23	
64	42	CMP2_IN0	CMP2_IN0	PTA12	CAN0_TX	FTM1_CH0	RMII0_RXD1/ MII0_RXD1	I2C2_SCL	I2S0_TXD0	FTM1_QD_PHA			
65	43	CMP2_IN1	CMP2_IN1	PTA13/ LLWU_P4	CAN0_RX	FTM1_CH1	RMII0_RXD0/ MII0_RXD0	I2C2_SDA	I2S0_TX_FS	FTM1_QD_PHB		LLWU_P4	
66	44	DISABLED		PTA14	SPI0_PCS0	UART0_TX	RMII0_CRS_DV/ MII0_RXDV	I2C2_SCL	I2S0_RX_BCLK	I2S0_TXD1			
67	45	DISABLED		PTA15	SPI0_SCK	UART0_RX	RMII0_TXEN/ MII0_TXEN		I2S0_RXD0				

Pinout

	1	2	3	4	5	6	7	8	9	10	11	
A	PTD7	PTD5	PTD4/ LLWU_P14	PTC19	PTC14	PTC13	PTC8	PTC4/ LLWU_P8	PTD9	PTD8	NC	A
B	PTD10	PTD6/ LLWU_P15	PTD3	PTC18	PTC15	PTC12	PTC7	PTC3/ LLWU_P7	PTC0	PTB16	PTB12	B
C	PTD12	PTD11	PTD2/ LLWU_P13	PTC17	PTC11/ LLWU_P11	PTC10	PTC6/ LLWU_P10	PTC2	PTB19	PTB11	PTB13	C
D	PTD14	PTD13	PTD1	PTD0/ LLWU_P12	PTC16	PTC9	PTC5/ LLWU_P9	PTC1/ LLWU_P6	PTB18	PTB10	PTB8	D
E	PTD15	PTE2/ LLWU_P1	PTE1/ LLWU_P0	PTE0	VDD	VDD	VDD	PTB23	PTB17	PTB9	PTB7	E
F	USB0_DP	USB0_DM	PTE6	PTE3	VDDA	VSSA	VSS	PTB22	PTB21	PTB20	PTB6	F
G	VOUT33	VREGIN	VSS	PTE5	VREFH	VREFL	VSS	PTB3	PTB2	PTB1	PTB0/ LLWU_P5	G
H	ADC0_DP1	ADC0_DM1	ADC0_SE16/ CMP1_IN2/ ADC0_SE21	NC	PTE24	PTE26	PTE4/ LLWU_P2	PTA1	PTA3	PTA17	PTA29	H
J	ADC1_DP1	ADC1_DM1	ADC1_SE16/ CMP2_IN2/ ADC0_SE22	PTA11	PTE25	PTA0	PTA2	PTA4/ LLWU_P3	PTA10	PTA16	RESET_b	J
K	ADC0_DP0/ ADC1_DP3	ADC0_DM0/ ADC1_DM3	NC	DAC1_OUT/ CMP0_IN4/ CMP2_IN3/ ADC1_SE23	DAC0_OUT/ CMP1_IN3/ ADC0_SE23	VBAT	PTA5	PTA12	PTA14	VSS	PTA19	K
L	ADC1_DP0/ ADC0_DP3	ADC1_DM0/ ADC0_DM3	VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18	XTAL32	EXTAL32	VSS	RTC_ WAKEUP_B	PTA13/ LLWU_P4	PTA15	VDD	PTA18	L
	1	2	3	4	5	6	7	8	9	10	11	

Figure 34. 121 XFBGA Pinout Diagram

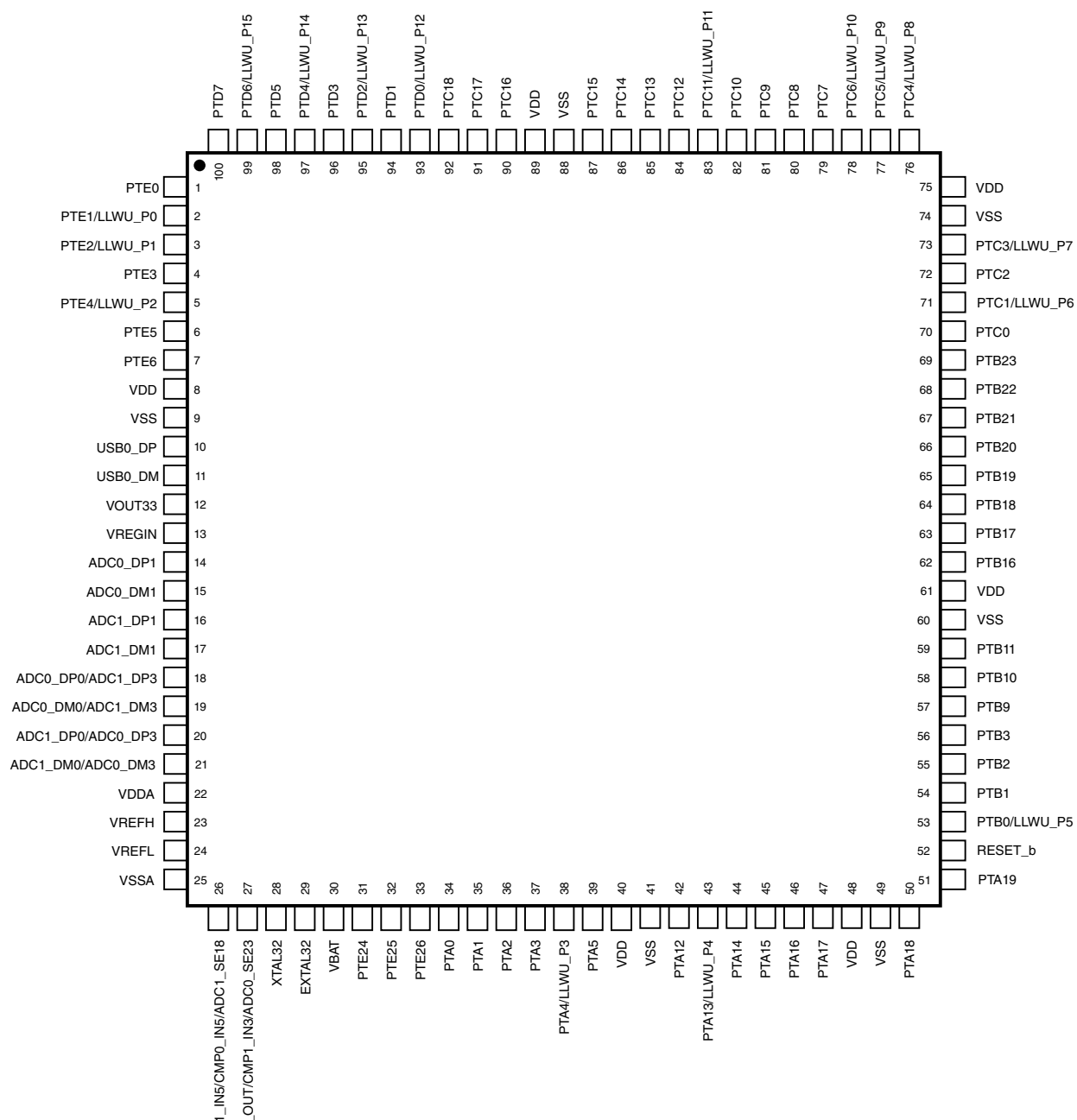


Figure 35. 100 LQFP Pinout Diagram

6.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to nxp.com and perform a part number search for the following device numbers: MK24

7 Part identification

7.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

7.2 Format

Part numbers for this device have the following format:

Q K## A M FFF R T PP CC N

7.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
Q	Qualification status	- M = Fully qualified, general market flow - P = Prequalification
K##	Kinetis family	K24 = USB with high RAM density
A	Key attribute	- D = Cortex-M4 w/ DSP - F = Cortex-M4 w/ DSP and FPU
M	Flash memory type	- N = Program flash only - X = Program flash and FlexMemory
FFF	Program flash memory size	32 = 32 KB 64 = 64 KB 128 = 128 KB 256 = 256 KB 512 = 512 KB 1M0 = 1 MB 2M0 = 2 MB

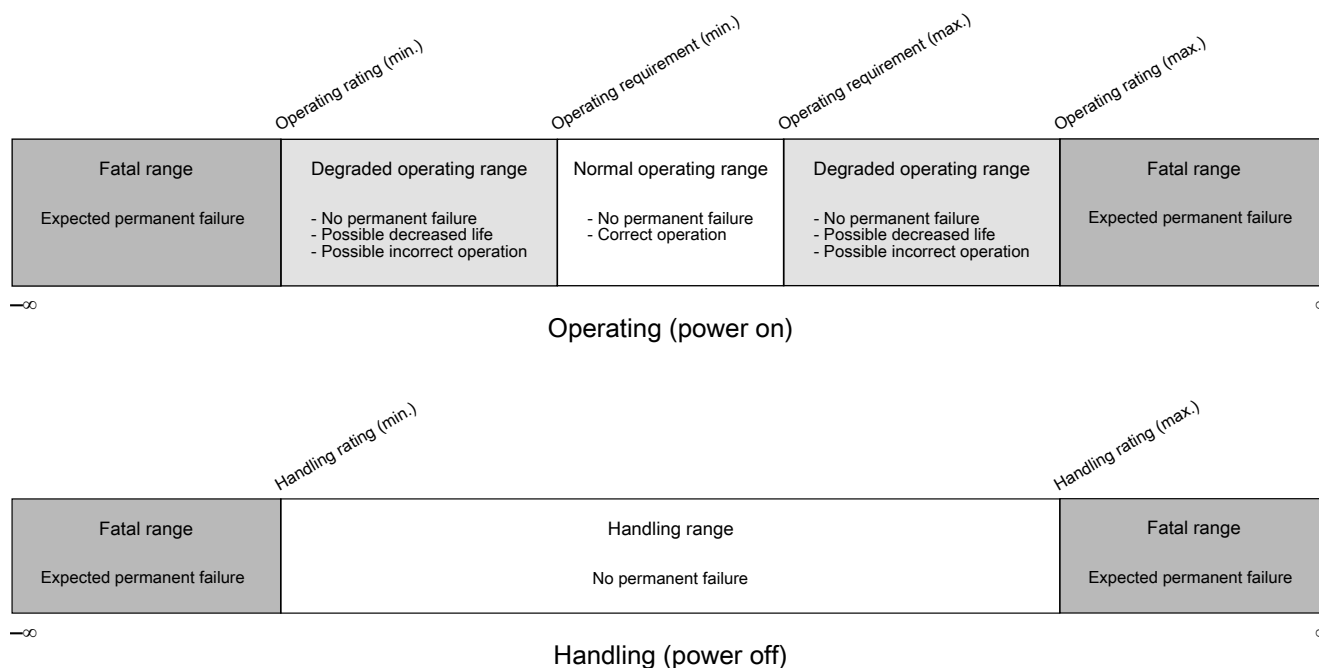
Table continues on the next page...

8.3 Typical-value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
T_A	Ambient temperature	25	°C
V_{DD}	Supply voltage	3.3	V

8.4 Relationship between ratings and operating requirements



8.5 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.